

Product Name: TLP2160

Package Name: SO8

1. Thermal tests

Test Item	Test Condition	Failure Size / Sample Size
Heat resistance (Reflow)	Peak : 260 deg.C(a moment) Reflow zone : 230 deg.C 30 to 50 s Preheat : 180 to 190 deg.C , 60 to 120 s 2 times	0 / 32
Heat resistance (Flow)	Peak : 260 deg.C Immersion time : 10 s Once	0 / 32
Heat resistance (Iron)	Temperature of the iron tip : 350 deg.C Time : 3 s Once	0 / 32
Temperature cycling	- 55 deg.C(30 min) to 125 deg.C(30 min) ,100 cycles	0 / 50

2. Mechanical tests

Test Item	Test Condition	Failure Size / Sample Size
Solderability	Solder bath : Sn-Ag-Cu 245 deg.C , 5 s ,once (using Flux) Solder bath : Sn-Pb 230 deg.C , 5 s ,once (using Flux)	0 / 11
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-	-	-
-	-	-
-	-	-

3. Life tests

Test Item	Test Condition	Failure Size / Sample Size
Steady state operation	Ta = 125 deg.C, IF = 15mA, IO = 10mA, VCC = 6V ,1000 h	0 / 30
High temp. bias	Ta = 125 deg.C, IF = 15mA, VCC = 6V ,1000 h	0 / 30
High temp. storage	Ta = 150 deg.C ,1000 h	0 / 30
High temp. high humidity storage	Ta = 85 deg.C, RH = 85% ,1000 h	0 / 30
Pressure cooker test	Ta = 121 deg.C(203kPa)(Unsaturated) ,96 h	0 / 20
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Estimated Failure Rate

Product Name	Estimated failure rate
TLP2160	0.84 Fit or less

Above estimated value is determined with the standard operation under the general environment:*

*The general environment here means the conditions of $T_j = 55$ degree C and no application of surge and so on.

The Estimated Failure Rate contained herein represents the result of our internal product reliability tests, and is provided for your reference only.
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For detailed reliability test information, please contact your Toshiba sales representative.

Moisture Absorption Control Level (Moisture Sensitivity Level)

Product Name : TLP2160

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Always store the Product under moisture sensitivity level equivalent to level 1 (JEDEC J-STD-020 Moisture Sensitivity Level). In the event the Product is stored otherwise, the applicable warranty, if any, is void.

Always perform reflow soldering in accordance with methods and conditions as specified in applicable engineering documents or specifications provided by Toshiba, or as instructed in writing by your TOSHIBA sales representative.

In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

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